

US-PAT-NO: 6232212
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TITLE: Flip chip bump bonding

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Brief Summary Text - BSTX (7):

There is a growing choice of methods for applying solder bumps to IC chips and interconnection substrates. The most common, is to print a pattern of solder paste through a screen or stencil, then remove the stencil and reflow the solder. In a similar approach, which eliminates the paste, solder is evaporated through a shadow mask onto the UBM. In both cases, reliability problems increase as the features in the stencil or mask are shrunk to meet demands for ever smaller interconnection pitch. Stencil and shadow mask techniques are, in general, limited to applications in which bump pitch is of the order of 200 .mu.m or more.